



厦 门 华 联 电 子 有 限 公 司

Xiamen Hualian Electronics Co., Ltd.

产 品 规 格 书

SPECIFICATION

产品名称：绿色发光二极管

DESCRIPTION: GREEN BRIGHT LED

型号 MODEL: HFA031C-50-02

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1、特点 (FEATURES) :

- 驱动电流低，发光强度高。 Low Drive Current, High Intensity of Light Emission.
- 快速响应时间，可用脉冲驱动。 Fast Response Time, Pulse Driven.
- 环氧树脂无色透明封装。 Water Clear Molding.

2、极限参数 (ABSOLUTE MAXIMUM RATINGS) (Ta=25℃):

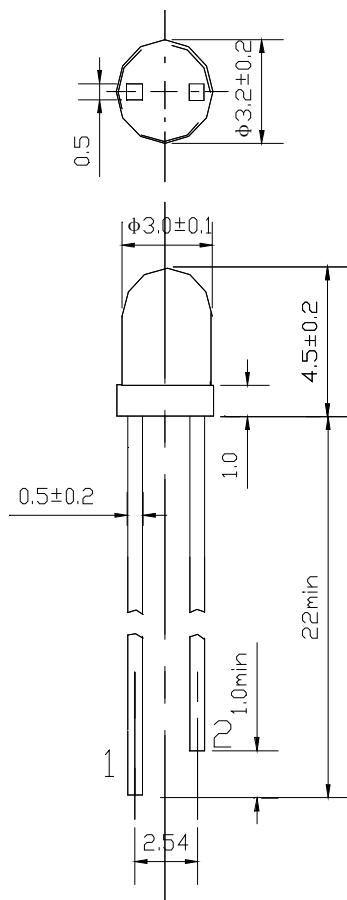
参数名称 PARAMETER	符号 SYMBOL	额定值 RATING	单位 UNIT
正向电流 Forward Current	I_{FM}	30	mA
反向电压 Reverse Voltage	V_R	5	V
耗散功率 Power Dissipation	P_D	140	mW
工作温度 Operating Temperature	T_{opr}	-20~+85	℃
贮存温度 Storage Temperature	T_{stg}	-40~+100	℃
焊接温度 (5 秒) (1) Soldering Heat (5s)	T_{sol}	260	℃

(1) 离器件本体 2 mm 以上 Up to 2 mm from the body.

3、光电参数 (OPTOELECTRIC CHARACTERISTICS) (Ta=25℃):

参数 Parameter	符号 Symbol	测试条件 Test Condition		最小值 Min.	典型值 Typ.	最大值 Max.	单位 Unit
正向电压 Forward Voltage	V _F	I _F =20mA		-	3.5	4.0	V
反向电流 Reverse Current	I _R	V _R =5V		-	-	50	μA
发光强度 Luminous Intensity	I _v	I _F =10mA	D3	450	-	800	mcd
			D4	700	-	1200	
峰值波长 Peak Emitting Wavelength	λ _D	I _F =20mA	B1	497	-	505	nm
			B2	505	-	510	
			B3	510	-	515	
半宽度 Spectrum Half Width	Δ λ	I _F =20mA		-	35	-	nm
半强角 Viewing Angle	2 θ _{1/2}	I _F =10mA		-	50	-	Deg

4、外形尺寸 (DIMENSION)



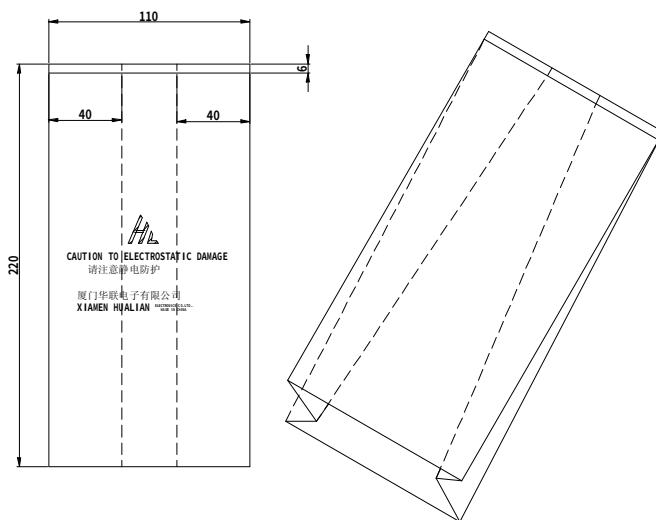
1. 正极 Anode
2. 负极 Cathode

未注公差: ± 0.2 mm

6. 包装方式 Packing

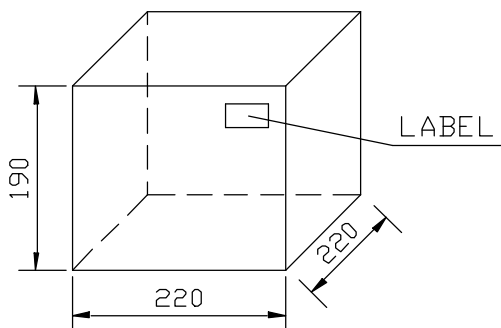
6.1 用 $220 \times 110 \text{mm}^2$ 防静电塑料袋内包装, 1000 只/袋。

Internally packed with $220 \times 110 \text{mm}^2$ plastic bag anti-statically, 1000pcs/bag.



6.2 外包装用纸盒 ($220 \times 220 \times 190 \text{mm}^3$), 15000 只/盒。

Externally Packed with $220 \times 220 \times 190 \text{mm}^3$ cartons, 15000 pcs/carton.



6.3 标识 Label

 Xiamen Hualian Electronics Co., Ltd.	P/N: _____
	Lot No.: _____
	Qty.: _____
	Insp.: _____

7. 注意事项 Precautions

7.1 引线成型 Forming

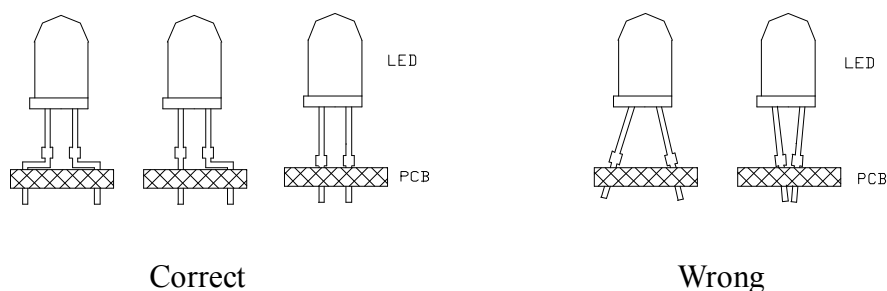
1) 引线成型需在焊接前完成。Leads should be formed before soldering.

- 2) 不能以引线基材为支点成型。Do not form the leads with their bases as a fulcrum.
- 3) 成型位置应离环氧本体 5mm 以上。Forming location should be up to 5mm from the epoxy body.

7.2 安装 Installation

LED 安装在 PCB 上，不能造成对引线施加压力。

Installation on PCB do not apply physical stress to the leads when mounting LED lamps on PCB.



7.3 焊接 Soldering

- 1) 环氧不可浸入锡槽内。Do not dip epoxy body into solder bath.
- 2) 加热过程中不能对引线施加压力。Do not apply stress to the leads while they are heated.
- 3) 使用电烙铁焊接时，电烙铁的功率应小于等于 30W，焊接时间应小于 3 秒。

When soldering LED, the solder iron power should be not more than 30W and with the soldering time not more than 3 seconds.

9.4 清洗 Cleaning

- 1) 在任何情况下，清洗时间应在常温 1 分钟之内进行。

In any case, the cleaning time should be 1 minute or less at a normal temperature.

- 2) 不可用水清洗，以免腐蚀引线，推荐使用酒精。

Do not clean LEDs with water as the remains may rust the leads. Alcohol is suggested to be used.

- 3) 用超声波清洗 LED 时，超声功率和时间应分别小于 300W 和 30 秒；PCB 和 LED 不能接触振荡器；不能使 PCB 上 LED 产生共振。

When LEDs are ultrasonic-washed, use the ultrasonic output power of less than 300W and the time of less than 30s; do not let the PCB and LEDs touch on the oscillator; do not resonate the LEDs attached on the PCB.

7.5 超高亮 LED 为静电敏感器件，所以静电和电涌会损坏 LED。要求使用时佩带防静电腕带，

所有的装置、设备、机器、桌子、地面都必须防静电接地。

The ultra bright LED is an electrostatic insensitive device, so static electricity and surge will damage the LED. It is required to wear a wrist-band when handling the LED. All device, equipment, machinery, desk and ground must be properly grounded.

8. 建议使用方式 Suggested way of usage.

LED 使用时必须串联一个保护电阻，正向直流电流为 20mA 左右。

When using LED, it must use a protective resistor in series with DC current about 20 mA.